

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. : 10/789,799                      Confirmation No. : 9449  
Applicant : KUO, Frank  
Filed : February 27, 2004  
T.C./A.U. : 1732  
Examiner : LEE, Edmund  
  
Title : Encapsulation Method and Leadframe for Leadless Semiconductor  
         Packages  
Docket No. : VISH-4123.DIV

AMENDMENT AND RESPONSE TO OFFICE ACTION

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action of January 3, 2007, Applicant respectfully requests further examination and reconsideration of the above-identified patent application in view of the arguments set forth below.